

## Effects of Channel and Crystalline Orientations on the Electron Mobility in MOSFETs Fabricated on (114) and (5 5 12)-Silicon Substrates

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This work reports the measurement of the electron mobility in the inversion layer of MOSFETs fabricated on Si(114) and Si(5 5 12), for medium and high effective transverse electric fields,  $E_{eff}$ . These substrates were chosen because their surfaces present row-like features with a relatively long (1-digit nanometers) inter-row periodicity [1-2] that could be used to develop nm-like MOSFETs. We studied the channel mobility in these surfaces as a function of the channel direction [1-4].

N-channel MOSFETs were simultaneously fabricated on (001) (used as a reference), (114), and (5 5 12) Si wafers. The channel was oriented at 0, 15, 30, 45, 50, 75, and 90° away from  $[\bar{1}10]$ . We measured the channel conductance  $g_d$  in  $W/L=45\mu\text{m}/45\mu\text{m}$  MOSFETs operating in the linear region ( $v_{ds}=50$  mV), and the effective mobility,  $\mu_{eff}$ , was calculated as [5]:

$$\mu_{eff} = \frac{L_{eff}}{W_{eff}} \frac{g_d}{Q_n}$$

As can be seen in Fig. 1 for the (114)-MOSFETs, the effective mobility decreases as the angle of the channel with respect to the  $[\bar{1}10]$  direction varies from 0° (parallel) to 90° (perpendicular to the nanogrooves); this behavior was similar to that obtained for the (5 5 12)-MOSFETs. These results mean that, in opposition to the isotropy found in (001)-MOSFETs (where the dependence of mobility on the channel angle was practically null), the channel electron mobility in these specific high index Si substrates is highly anisotropic at any  $E_{eff}$ . Thus, the surface roughness scattering is the dominant process and it depends strongly on the channel orientation. This fact can be explained by the peculiar row-like surface topography with quite regular nanogrooves running along the  $[\bar{1}10]$  direction. We believe that these nanogrooves can also behave as nanotubes, thus improving the carrier transport when the MOSFET channel runs along this direction; on the other hand, the roughness scattering is enhanced when the channel is tilted away the  $[\bar{1}10]$  direction, thus degrading the mobility.

Fig. 2 shows a comparison of the highest mobility measured (channel oriented at 0°) for the three substrate orientations used in this work. For  $E_{eff} \sim 1\text{MV}/\text{cm}$ , the electron mobility in Si(5 5 12) is as high as the mobility in

Si(001), whereas the mobility for (114)-MOSFETs is even higher. This fact can be of great technological relevancy since in current MOS technologies is common to find oxide thicknesses of the order of 2-3 nm and gate voltages of around 1 volt, which leads to  $E_{eff} > 1\text{MV}/\text{cm}$ .

At the time of the conference the results will be discussed in terms of phonon and surface scattering mechanisms, and a single model for effective electron mobility in these orientations will be proposed.

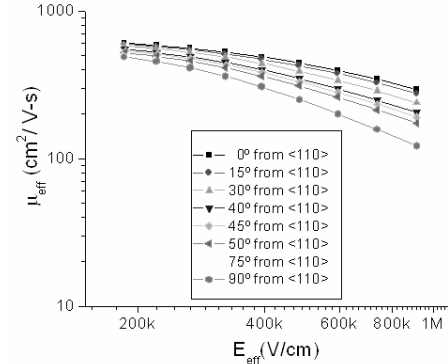


Fig. 1. Effective electron mobility as a function of the channel direction for (114)-MOSFETs. The mobility behavior is similar for the (5 5 12) case.

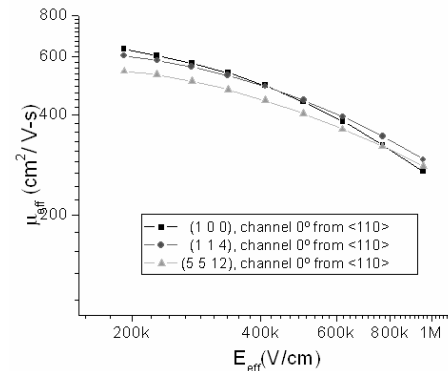


Fig.2. Electron mobility as a function of the crystal orientation for channels oriented at 0°.

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### References

- [1]. A.A. Baski, S.C. Erwin and L.J. Whitman, Surface Science, vol. 392, pp 69-85, 1997.
- [2]. S.C. Erwin, A.A. Baski, and L.J. Whitman, Physical Review Letters, vol. 77, no. 4, pp 687-690, 1996.
- [3]. A.A. Baski, K.M.Saud and K.M. Jones, Applied Surface Science, vol. 182, pp 216-222, 2001.
- [4]. Y. Peng, T. Suzuki, H. Minoda, Y. Tanishiro and K. Yagi, Surface Science, vol. 493, pp 499-507, 2001.
- [5]. D.K. Schroeder, "Semiconductor Material and Device Characterization", John Wiley and Sons, 2006.